Solid-State Light. Done Right.

APPROVAL SHEET

AOT MODEL NAME	3030M
AOT PART NUMBER	3030M-B001
CUSTOMER NAME	General
DATE	2021/Oct.
Version	01

MAKER			CUSTOMER			
Prepared	Checked	Approved				
Nelson						

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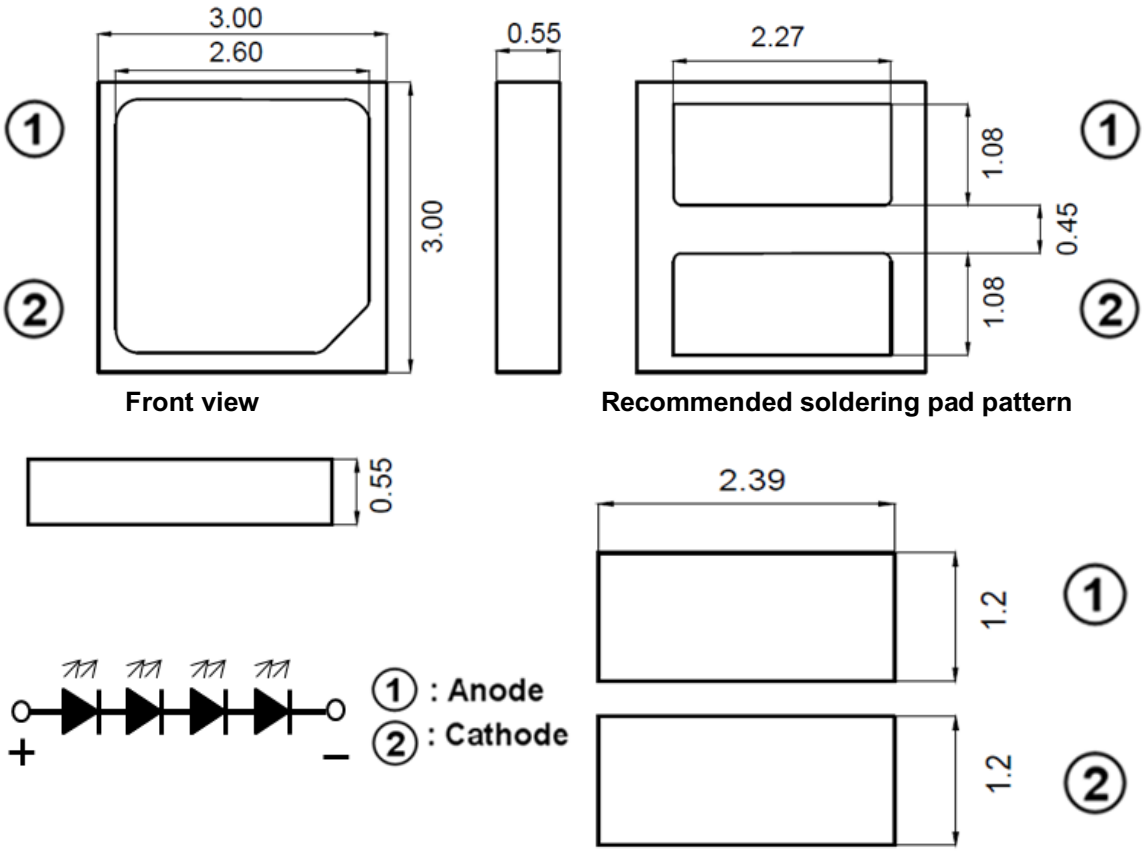
Revision Note

Date	Revision	Page	Version
2021-10-15	Initiate Document	--	01

Package Outline

Model name:3030M-B001
Unit: mm, Tolerance: ± 0.2 mm

Top view **Bottom view**



Item	Materials
Package	Heat-Resistant Polymer
Encapsulating	Silicone Resin(Non phosphor)
Electrode	Ag Plating Copper Alloy

- Four blue chips.
- High brightness SMD.
- Compact package outline (LxWxH) of 3.0 mm x 3.0 mm x 0.55 mm.
- Compatible with reflow soldering.
- Complies with RoHS Directive.

Optical/Electronic Characteristics (T_A=25˚C)

Item	Symbol	Condition	Min	Typ.	Max	Unit
Forward Voltage	V_F	I_F = 100mA	11.0	-	12.4	V
Luminous Flux	Φ_V	I_F = 100mA	600	-	850	mW
Thermal Resistance	R_{thj-s}	I_F = 100mA	5.7	7.2		˚C/W

* Tolerance of measurements of the Forward Voltage is ± 0.05 V.

* Tolerance of measurements of the Luminous Flux is ± 7%.

Absolute Maximum Ratings (T_A=25˚C)

Item	Symbol	Absolute Maximum Rating	Unit
Forward Current	I_F	250	mA
*Pulse Forward Current	I_{FP}	350	mA
Power Dissipation	P_D	3100	mW
Operating Temperature	T_{opr}	-30~+85 (I_F=100mA)	˚C
Storage Temperature	T_{stg}	-40~+100	˚C
Soldering Temperature	T_{sld}	Reflow Soldering : 260˚C for 10sec Hand Soldering : 350˚C for 3sec	
Junction Temperature	T_j	125	˚C
Forward Voltage at Low Current	V_{F2}	>7.6 (@1uA)	V

* I_{FP} Conditions : Pulse Width ≤ 10msec, and duty ≤ 1/10

* Max condition is not guarantee for life time

Group Definition of Forward Voltage

Rank	Condition	V_F(V)
S80	T_A=25˚C I_F=100mA	11.0-11.1
S81		11.1-11.2
S62		11.2-11.3
S63		11.3-11.4
S64		11.4-11.5
S65		11.5-11.6
S66		11.6-11.7
S67		11.7-11.8
S68		11.8-11.9
S69		11.9-12.0
S70		12.0-12.1
S71		12.1-12.2
S72		12.2-12.3
S73		12.3-12.4

Group Definition of Brightness

Rank	Condition	Luminous Flux(mW)
T600	T_A=25˚C I_F=100mA	600 ~ 650
T650		650 ~ 700
T700		700 ~ 750
T750		750 ~ 800
T800		800 ~ 850

Group Definition of Wavelength

Rank	Condition	Wd(nm)
WB	T_A=25˚C I_F=100mA	447.5 ~ 450.0
WC		450.0 ~ 452.5
WD		452.5 ~ 455.0

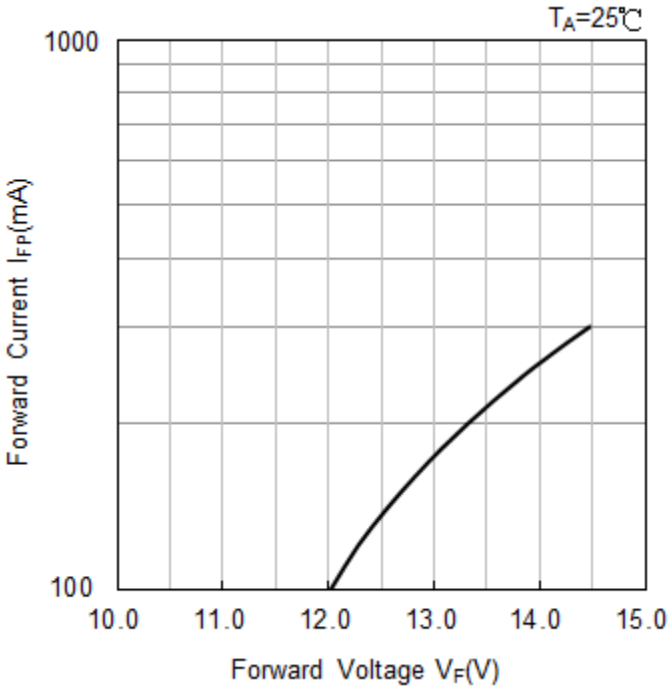
*A shipment shall consist of LEDs in a combination of above ranks.

The percentage of each rank in the shipment shall be determined by AOT.

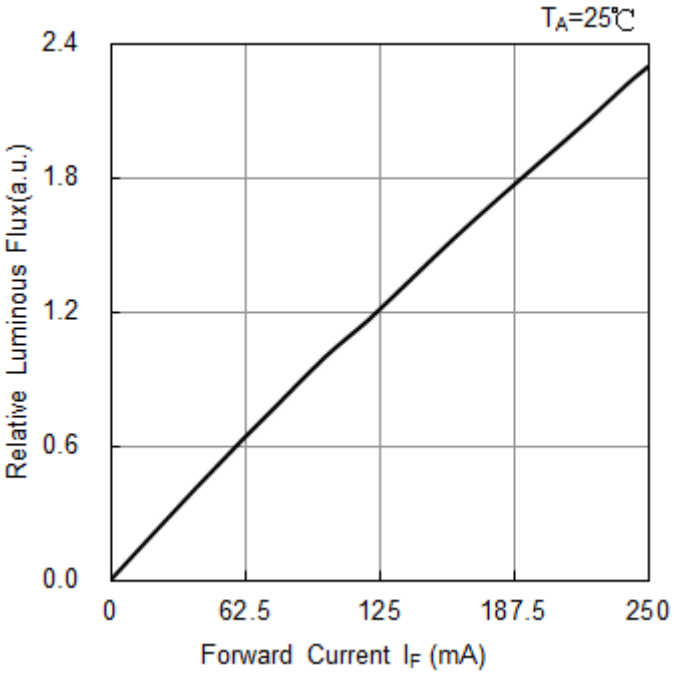
*The ranking information of LEDs can be found on the reel label.

Optical and electrical characteristics

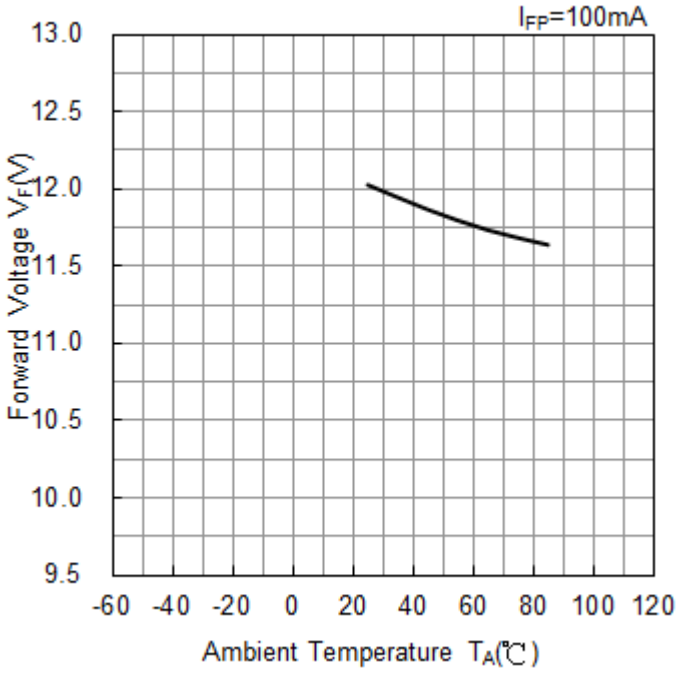
Forward Voltage vs. Forward Current



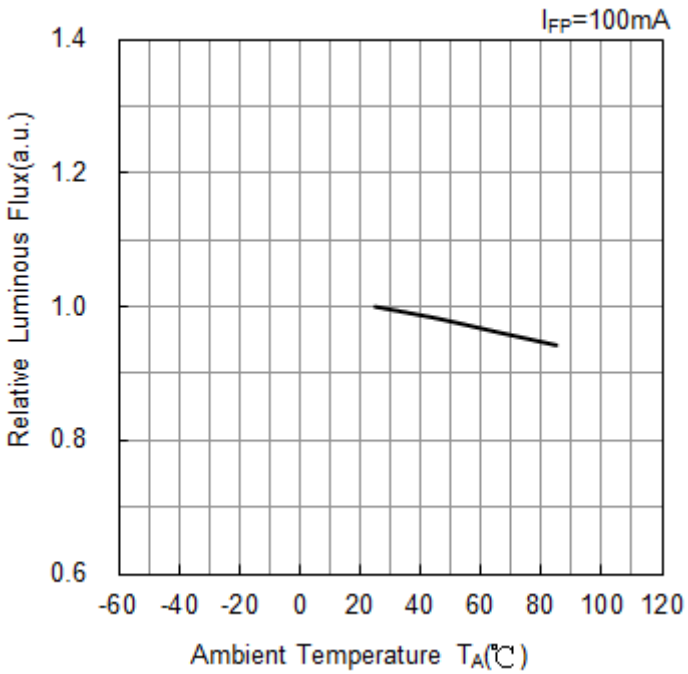
Forward Current vs. Relative Luminous Flux



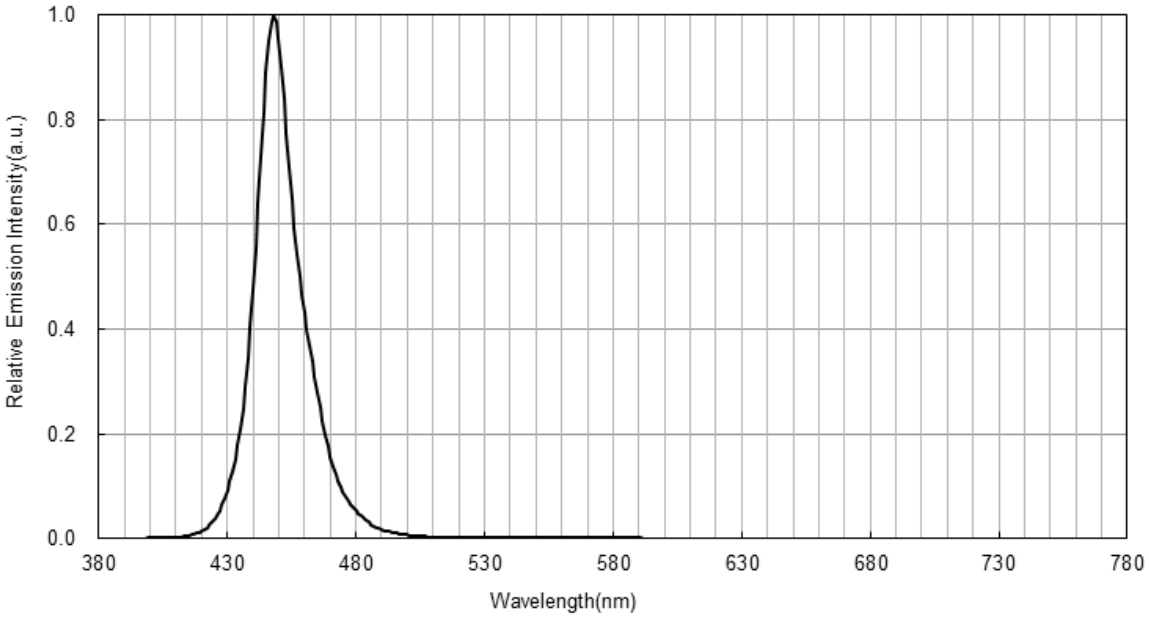
Ambient Temperature vs. Forward Voltage



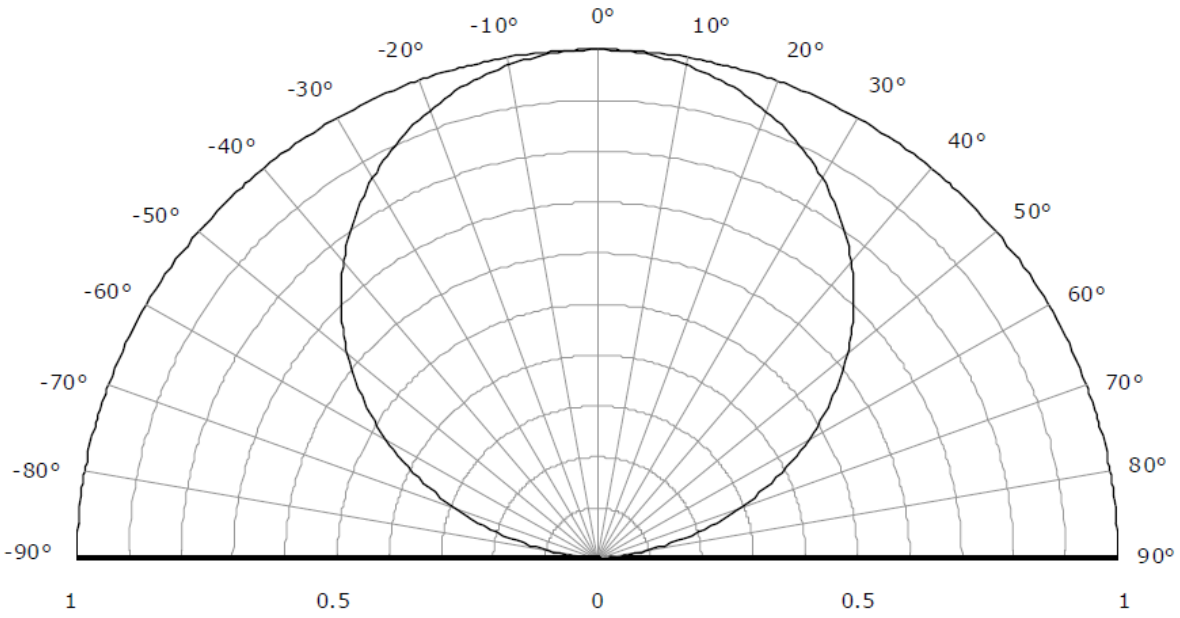
Ambient Temperature vs. Relative Luminous



Spectrum(T_A=25℃,I_F=100mA)



Radiation Pattern(T_A=25℃,I_F=100mA)



Recommended Reflow Soldering Conditions

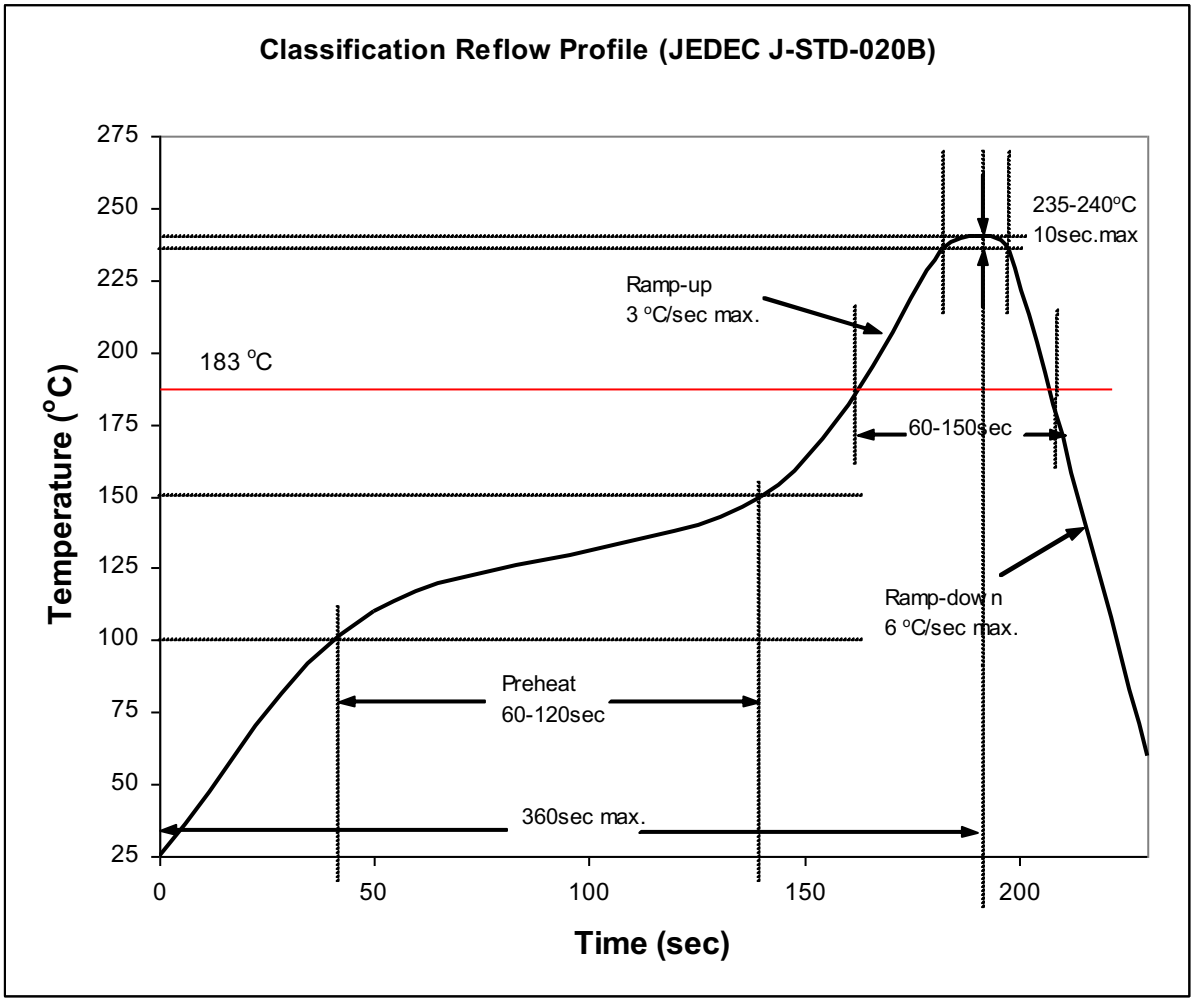
Surface Mounting Condition

In automatic mounting of the SMD LEDs on printed circuit boards, any bending, expanding and pulling forces or shock against the SMD LEDs should be kept min. to prevent them from electrical failures and mechanical damages of the devices.

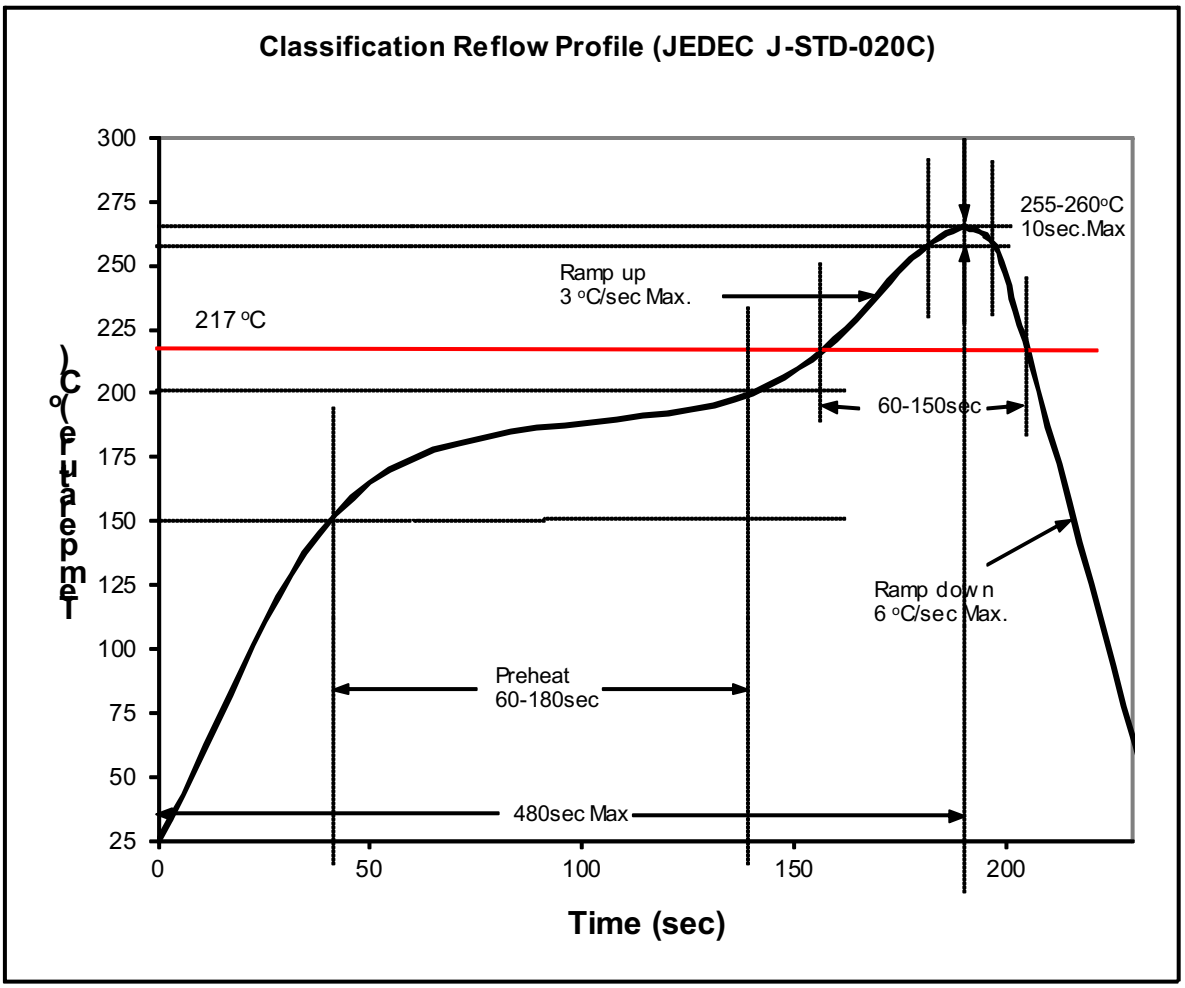
Soldering Reflow

-Soldering of the SMD LEDs should conform to the soldering condition in the individual specifications.
-SMD LEDs are designed for Reflow Soldering.
-In the reflow soldering, too high temperature and too large temperature gradient such as rapid heating/cooling may cause electrical & optical failures and damages of the devices.
-AOT cannot guarantee the LEDs after they have been assembled using the solder dipping method.

1) Lead Solder



2) Lead-Free Solder

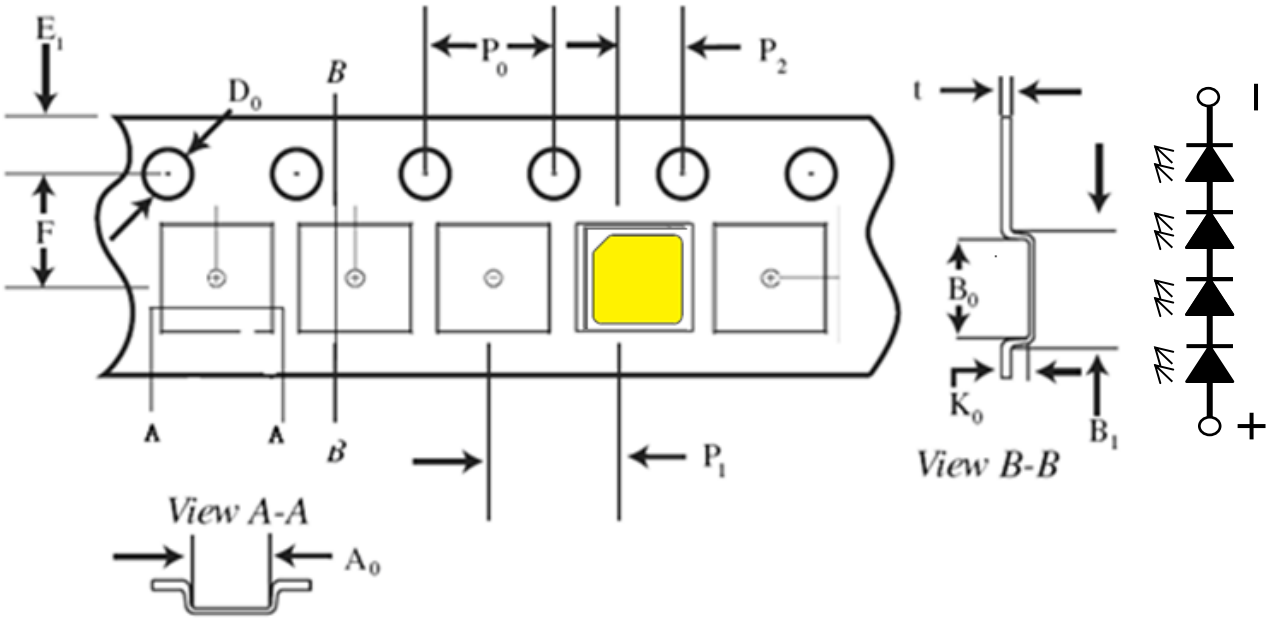


3) Manual Soldering Conditions

- Lead Solder
  Max. 300˚C for Max. 3sec, and only one time.
- Lead-free Solder
  Max. 350˚C for Max. 3sec, and only one time.

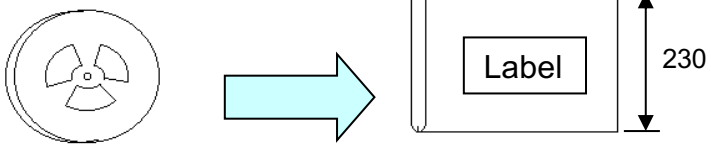
- There is possibility that the brightness of LEDs is decreased, which is influenced by heat or ambient atmosphere during reflow. It is recommended to use the nitrogen reflow method.
- After LEDs have been soldered, repair should not be done. As repair is unavoidable, a double-head soldering iron should be used. It should be confirmed beforehand whether the characteristics of the LEDs will be damaged by repairing or not.
- Reflow soldering should not be done more than two times.

Dimensions (Unit :mm)



Item	Spec.	Tolerance(mm)	Item	Spec.	Tolerance(mm)
W	8.00	±0.10	P2	2.00	±0.05
E	1.75	±0.10	t	0.25	±0.02
F	3.50	±0.05	A0	3.16	±0.05
D0	1.50	+0.10	B0	3.16	±0.05
D1	0.5	±0. 05	K0	0.71	±0.05
P0	4.00	±0.10			

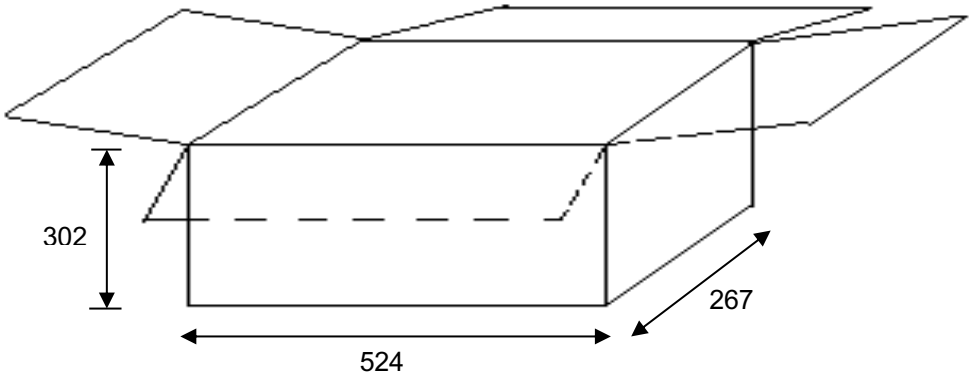
Packing Formation



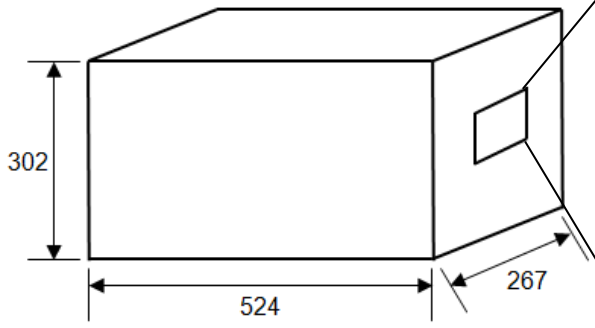
Diameter : 178 mm
Width : 8 mm
3,500 pcs/Reel
Antistatic Reel

MBB Bag
+5g drying agent
+Humidity card
1 Reel / Bag

50 Bags /1 Carton
⇒ 175,000 pcs/ 1Carton



Package Outlook



Advanced Optoelectronic Technology Inc.	
Customer	
PO No.	
Part No.	
Quantity	
Packing Date	
Carton No.	
Ship No.	
QC Check	
備註	

Solid-State Light. Done Right.

Reel Label Definition

SAP. No.

SMD LED .
Part Number : XXXXX-XXXX
Brightness : A
CIE : B
VF : C
Quantity : nn ea
Serial No : SM0yymmddxxxx
Cust. PN. : XXXXX-XXXX

A : Iv value.
B : CIE value noted
C : Vf value.
nn : Quantity of LED

SHyymmddxxx : yy : year, mm : month, dd : day, xxx : reel no

*Reel Label to fill in practice data of all LED characteristic

Reliability Test

No.	Test Item	Standard Test Method	Test Conditions	Note	Number of Damaged
1	Room Temp. Life Test	Internal Ref.	T_A=25 ˚C,I_F=100mA	1000 hrs	20
2	High Temp. Operating Life Test	JESD22-A108	T_A=65 ˚C,I_F=100mA	1000 hrs	20
3	High Temp. Operating Life Test	JESD22-A108	T_A=85 ˚C,I_F=100mA	1000 hrs	20
4	High Temp. Storage Test	JESD22-A103	T_A=85 ˚C	1000 hrs	20
5	Low Temp. Operating Life Test	JESD22-A108	T_A=-40 ˚C,I_F=100mA	1000 hr	20
6	Wet High Temp. Operating Life Test	JESD22-A119	60 ˚C 95%RH,I_F=100mA	1000 hr	20
7	Temperature and humidity cycle test	IEC68-2-38	25℃~65℃~-10℃,90% RH 24hr per cycle	10 cycles	20
8	Thermal Cycling Test	JESD22-A106	-40C ~ 100C ,30min Transform time 5min	300 cycles	50

Criteria for Judging Damage

Item	Symbol	Test Conditions	Criteria for Judgement	
			Min.	Max.
Forward Voltage	V_F	I_F =100mA	-	*U.S.L×1.1
Luminous Flux	Φ v	I_F =100mA	*L.S.L×0.7	-

* U.S.L: Upper Standard Level

* L.S.L: Lower Standard Level

Cautions

(1) Moisture Proof Package

The moisture proof package should be used to prevent moisture in the package as the moisture may Cause damage to optical characteristics of the LEDs.

The aluminum bag with zipper is used for moisture proof package. And, the moisture absorbent Material, Silica gel, is inserted into aluminum bag.

(2) Storage:

Storage Conditions

Before opening the package:

The LEDs should be kept at 30˚C or less than 90%RH or less. The LEDs should be used within a year. When storing the LEDs, moisture proof packaging with absorbent material is recommended.

After opening the package:

After open the package, the LED should be kept at 30˚C, 60%RH or less. The LED should be soldered within 168 hours (7 days) after opening the package. If unused LEDs remain, it should be stored in moisture proof condition.

(3) Heat Generation

Thermal design of the end products is of paramount importance. The heat generation must be taken into design consideration when using the LED. The coefficient of the temperature increase per input electric power is affected by the thermal resistance of the circuit board and density of LED placement on the board, as well as other components.

(4) Static Electricity

Static electricity or surge voltage damages the LEDs. All equipment and machinery must be properly grounded. It is recommended to use a wristband or anti-electrostatic glove when handing the LEDs. When inspecting the final products in which LEDs were assembled, it is recommended to check whether the assembled LEDs are damaged by static electricity or not. It is easy to find static-damaged LEDs by a light-on test or a Vf test at a lower current. (Below 1mA is recommended).

Criteria: V_F>7.6V at I_F=1uA

(5) Cleaning

Use isopropyl alcohol as a solvent for cleaning the LEDs. The other solvent may dissolve the LEDs package and the epoxy.

Ultrasonic cleaning should not be done.

(6) Electrostatic Discharge (ESD)

The products are sensitive to static electricity or surge voltage, An ESD event may damage its die or reduce its reliability performance. When handling the products, measures against electro static discharge, including the followings, are strongly recommended.

Eliminating the charge;

Wrist strap, ESD footwear and garments, ESD floors

Grounding the equipment and tools at workstation

ESD table / shelf mat (conductive materials)

Proper grounding techniques are required for all devices, equipment and machinery used in the assembly of the products, Also note that surge protection should be considered in the design of customer products.
If tools or equipment contain insulating materials, such as glass or plastic, proper measures against electro static discharge, including the followings are strongly recommended.

Dissipating the charge with conductive materials

Preventing the charge generation with moisture

Neutralizing the charge with ionizer

(7) Others

When using the LEDs, it must care that the reverse voltage will not exceed the absolute maximum rating.
The LED light is enough to injure human eyes, so it should avoid looking at LED light directly.

NOTE.

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